

GENERAL DESCRIPTION

The 74LVTN16245 is a 16-bit high-performance transceiver for 3.3V V_{CC} operation, but with the capability to provide an interface to 5V system environment. The non-inverting 3-state bus compatible outputs are available in both sending and receiving directions.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. The direction control (nDIR) input determines the direction of the data flow. nDIR (active-high) enables data from nAn port to nBn port. nDIR (active-low) enables data from nBn port to nAn port. The output enable ($n\overline{OE}$) input, when high, disables both nAn and nBn ports by placing them in a high-impedance state.

FEATURES

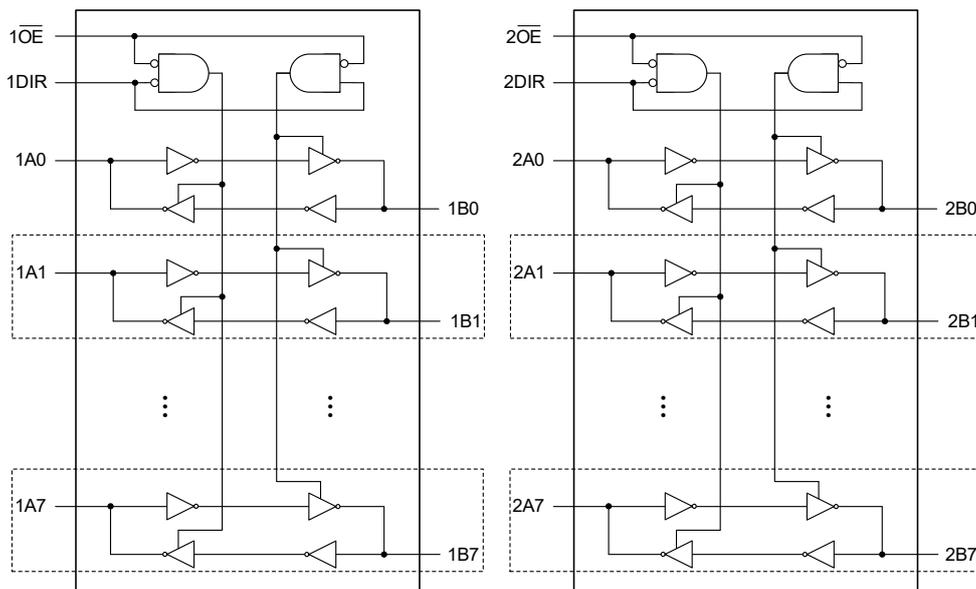
- **Wide Operating Voltage Range: 2.7V to 3.6V**
- **Input and Output Interface Capability to 5V System Environment**
- **+64mA/-32mA Output Current**
- **3-State Outputs Drive Bus Lines Directly**
- **Power-Up and I_{OFF} 3-State**
- **-40°C to +125°C Operating Temperature Range**
- **Available in a Green TSSOP-48 Package**

FUNCTION TABLE

CONTROL INPUT		INPUT/OUTPUT	
$n\overline{OE}$	nDIR	nAn	nBn
L	L	nAn = nBn	Inputs
L	H	Inputs	nBn = nAn
H	X	Z	Z

H = High Voltage Level
 L = Low Voltage Level
 Z = High-Impedance State
 X = Don't Care

LOGIC DIAGRAM



PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
74LVTN16245	TSSOP-48	-40°C to +125°C	74LVTN16245XTS48G/TR	74LVTN16245 XTS48 XXXXX	Tape and Reel, 2500

MARKING INFORMATION

NOTE: XXXXX = Date Code, Trace Code and Vendor Code.

XXXXX



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS ⁽¹⁾

Supply Voltage Range, V_{CC}	-0.5V to 4.6V
Input Voltage Range, V_I ⁽²⁾	-0.5V to 7.0V
Output Voltage Range, V_O ⁽²⁾	
3-State or High-State	-0.5V to 7.0V
Input Clamping Current, I_{IK} ($V_I < 0V$)	-50mA
Output Clamping Current, I_{OK} ($V_O < 0V$)	-50mA
Output Current, I_O	
High-State	-64mA
Low-State	128mA
Supply Current, I_{CC}	128mA
Ground Current, I_{GND}	-256mA
Junction Temperature ⁽³⁾	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (Soldering, 10s)	+260°C
ESD Susceptibility	
HBM	8000V
CDM	1000V

RECOMMENDED OPERATING CONDITIONS

Supply Voltage Range, V_{CC}	2.7V to 3.6V
Input Voltage Range, V_I	0V to 5.5V
High-Level Output Current, I_{OH}	-32mA
Low-Level Output Current, I_{OL}	64mA
Input Transition Rise or Fall Rate, $\Delta t/\Delta V$	10ns/V (MAX)
Operating Temperature Range	-40°C to +125°C

OVERSTRESS CAUTION

1. Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.
2. The input and output voltage ratings may be exceeded if the input and output clamp current ratings are observed.
3. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

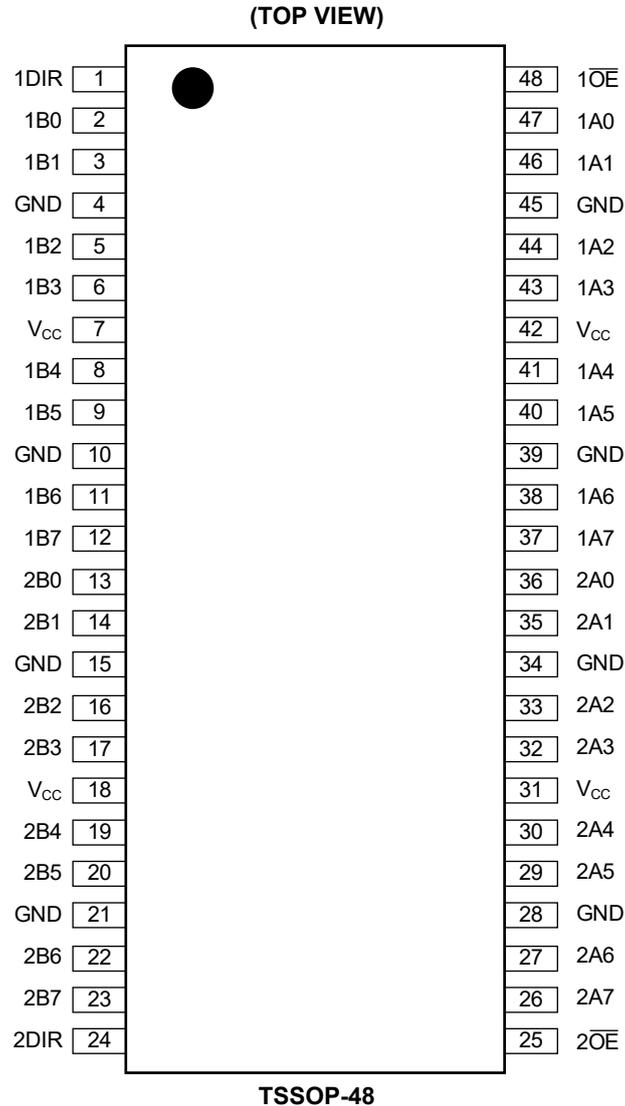
ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

PIN CONFIGURATION



PIN DESCRIPTION

PIN	NAME	FUNCTION
1, 24	1DIR, 2DIR	Direction Control Inputs.
2, 3, 5, 6, 8, 9, 11, 12	1B0, 1B1, 1B2, 1B3, 1B4, 1B5, 1B6, 1B7	Data Inputs/Outputs.
13, 14, 16, 17, 19, 20, 22, 23	2B0, 2B1, 2B2, 2B3, 2B4, 2B5, 2B6, 2B7	Data Inputs/Outputs.
4, 10, 15, 21, 28, 34, 39, 45	GND	Ground.
7, 18, 31, 42	V _{CC}	Supply Voltage.
48, 25	1OE, 2OE	Output Enable Inputs (Active-Low).
36, 35, 33, 32, 30, 29, 27, 26	2A0, 2A1, 2A2, 2A3, 2A4, 2A5, 2A6, 2A7	Data Inputs/Outputs.
47, 46, 44, 43, 41, 40, 38, 37	1A0, 1A1, 1A2, 1A3, 1A4, 1A5, 1A6, 1A7	Data Inputs/Outputs.

ELECTRICAL CHARACTERISTICS

(Full = -40°C to +125°C, all typical values are measured at $V_{CC} = 3.3V$ and $T_A = +25^\circ C$, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS	
Input Clamping Voltage	V_{IK}	$V_{CC} = 2.7V, I_{IK} = -18mA$	Full	-1.2	-0.78		V	
High-Level Input Voltage	V_{IH}	$V_{CC} = 2.7V$ to 3.6V	Full	2.0			V	
Low-Level Input Voltage	V_{IL}	$V_{CC} = 2.7V$ to 3.6V	Full			0.8	V	
High-Level Output Voltage	V_{OH}	$V_{CC} = 2.7V$ to 3.6V, $I_{OH} = -100\mu A$	Full	$V_{CC} - 0.05$	$V_{CC} - 0.001$		V	
		$V_{CC} = 2.7V, I_{OH} = -8mA$	Full	2.45	2.60			
		$V_{CC} = 3.0V, I_{OH} = -32mA$	Full	2.10	2.65			
Low-Level Output Voltage	V_{OL}	$V_{CC} = 2.7V, I_{OL} = 100\mu A$	Full		0.001	0.05	V	
		$V_{CC} = 2.7V, I_{OL} = 24mA$	Full		0.15	0.28		
		$V_{CC} = 3.0V, I_{OL} = 16mA$	Full		0.1	0.18		
		$V_{CC} = 3.0V, I_{OL} = 32mA$	Full		0.2	0.36		
		$V_{CC} = 3.0V, I_{OL} = 64mA$	Full		0.4	0.55		
Input Leakage Current	I_I	Control pins, $V_{CC} = 3.6V, V_I = V_{CC}$ or GND	Full		± 0.01	± 1	μA	
		Control pins, $V_{CC} = 0V$ or 3.6V, $V_I = 5.5V$	Full		0.01	5		
		Input/output data pins ⁽¹⁾ , $V_{CC} = 3.6V, V_I = 5.5V$	Full		1	5		
		Input/output data pins ⁽¹⁾ , $V_{CC} = 3.6V, V_I = V_{CC}$	Full		0.01	1		
		Input/output data pins ⁽¹⁾ , $V_{CC} = 3.6V, V_I = 0V$	Full	-2	-0.01			
Output Leakage Current	I_{LO}	Outputs in high-state when $V_O > V_{CC}$, $V_{CC} = 3.0V, V_O = 5.5V$	Full		1	30	μA	
Power-Up/Down Output Current	$I_{O_PU/PD}$	$V_{CC} \leq 1.2V, V_O = 0.5V$ to $V_{CC}, V_I = GND$ or V_{CC} , $n\overline{OE} = \text{don't care}$	+25°C		0.01	10	μA	
Power-Off Leakage Current	I_{OFF}	$V_{CC} = 0V, V_I$ or $V_O = 0V$ to 5.5V	Full		0.01	10	μA	
Supply Current	I_{CC}	$V_{CC} = 3.6V,$ $V_I = GND$ or $V_{CC},$ $I_O = 0A$	Outputs high	Full		16	90	μA
			Outputs low	Full		16	90	
			Outputs disabled ⁽²⁾	Full		16	85	
Additional Supply Current	ΔI_{CC}	Per input pin, $V_{CC} = 3.0V$ to 3.6V, one input at $V_{CC} - 0.6V$, other inputs at V_{CC} or GND	Full		0.2	80	μA	
Input Capacitance	C_I	nDIR and $n\overline{OE}$ inputs, $V_I = 0V$ or 3.0V	+25°C		6		pF	
Input/Output Capacitance	$C_{I/O}$	At input/output data pins, outputs disabled, $V_{I/O} = 0V$ or 3.0V	+25°C		9		pF	

NOTES:

- Other pins must be tied to V_{CC} or GND and should not be floating.
- I_{CC} is measured with outputs pulled to V_{CC} or GND.

DYNAMIC CHARACTERISTICS

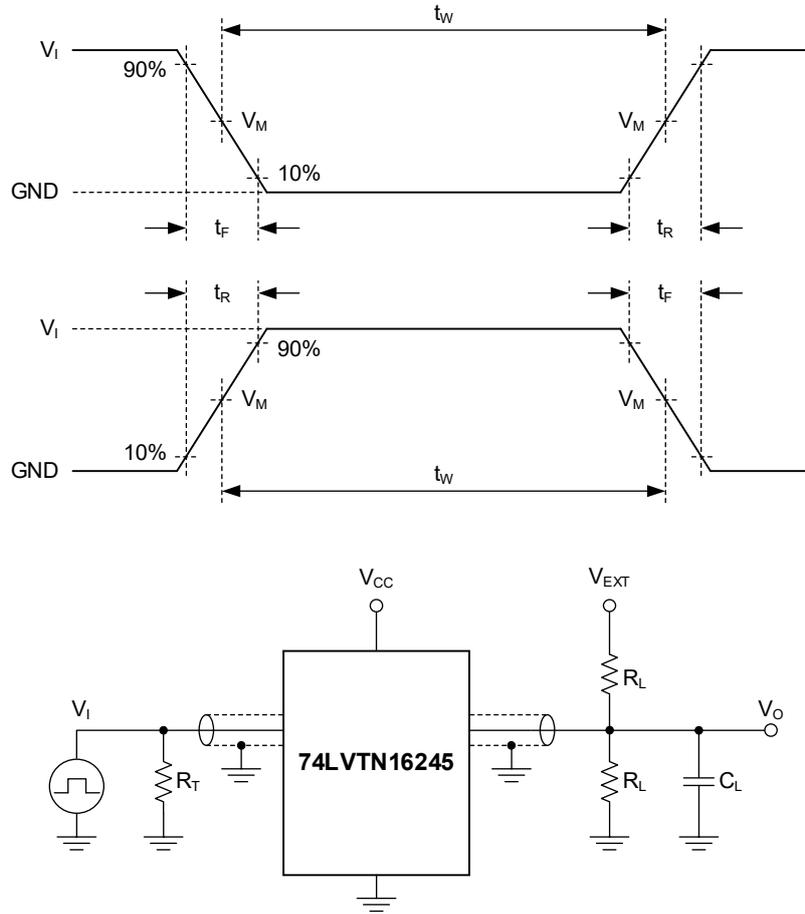
(See Figure 1 for test circuit. Full = -40°C to +125°C, all typical values are measured at $V_{CC} = 3.3V$ and $T_A = +25^\circ C$, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN ⁽¹⁾	TYP	MAX ⁽¹⁾	UNITS	
Low-to-High Propagation Delay	t_{PLH}	nAn to nBn or nBn to nAn, see Figure 2	$V_{CC} = 2.7V$	Full		3.6	8.5	ns
			$V_{CC} = 3.0V$ to 3.6V	Full	0.5	3.4	7.2	
High-to-Low Propagation Delay	t_{PHL}	nAn to nBn or nBn to nAn, see Figure 2	$V_{CC} = 2.7V$	Full		3.2	6.2	ns
			$V_{CC} = 3.0V$ to 3.6V	Full	0.5	3.0	5.6	
Off-to-High Propagation Delay	t_{PZH}	\overline{nOE} to nAn or nBn, see Figure 3	$V_{CC} = 2.7V$	Full		4.2	9.4	ns
			$V_{CC} = 3.0V$ to 3.6V	Full	0.5	4.0	7.8	
Off-to-Low Propagation Delay	t_{PZL}	\overline{nOE} to nAn or nBn, see Figure 3	$V_{CC} = 2.7V$	Full		4.0	6.5	ns
			$V_{CC} = 3.0V$ to 3.6V	Full	0.5	3.8	6.2	
High-to-Off Propagation Delay	t_{PHZ}	\overline{nOE} to nAn or nBn, see Figure 3	$V_{CC} = 2.7V$	Full		4.4	7.6	ns
			$V_{CC} = 3.0V$ to 3.6V	Full	0.5	4.0	7.0	
Low-to-Off Propagation Delay	t_{PLZ}	\overline{nOE} to nAn or nBn, see Figure 3	$V_{CC} = 2.7V$	Full		4.2	6.8	ns
			$V_{CC} = 3.0V$ to 3.6V	Full	0.5	4.0	6.5	

NOTE:

1. Specified by design and characterization, not production tested.

TEST CIRCUIT



Test conditions are given in Table 1.

Definitions for test circuit:

R_L : Load resistance.

C_L : Load capacitance (includes jig and probe).

R_T : Termination resistance (equals to output impedance Z_O of the pulse generator).

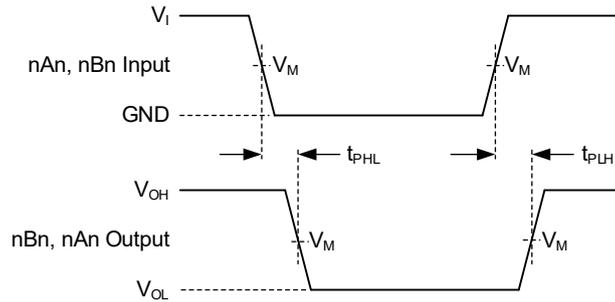
V_{EXT} : External voltage is used to measure switching time.

Figure 1. Test Circuit for Measuring Switching Times

Table 1. Test Conditions

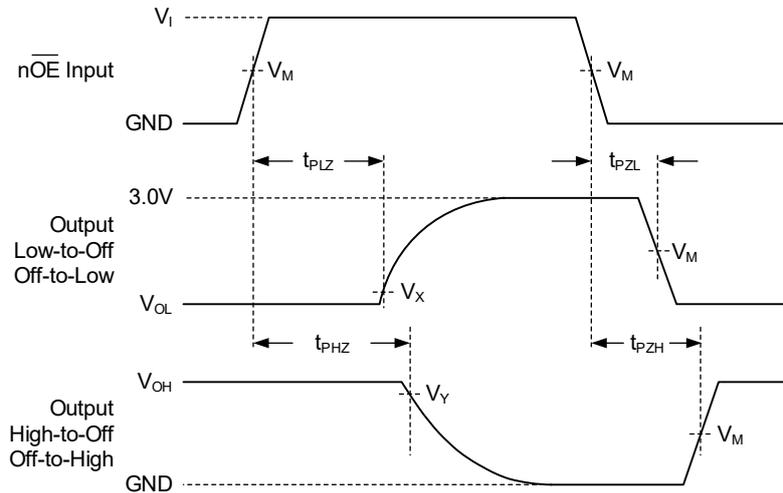
SUPPLY VOLTAGE	INPUT		LOAD		V_{EXT}		
V_{CC}	V_I	t_R, t_F	C_L	R_L	t_{PHZ}, t_{PZH}	t_{PLZ}, t_{PZL}	t_{PLH}, t_{PHL}
2.7V to 3.6V	2.7V	$\leq 2.5\text{ns}$	50pF	500 Ω	GND	6V	Open

WAVEFORMS



Test conditions are given in Table 1.
Measurement points are given in Table 2.
Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 2. Input (nAn, nBn) to Output (nBn, nAn) Propagation Delays



Test conditions are given in Table 1.
Measurement points are given in Table 2.
Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 3. Enable and Disable Times

Table 2. Measurement Points

SUPPLY VOLTAGE	INPUT		OUTPUT		
V_{CC}	V_I	$V_M^{(1)}$	V_M	V_X	V_Y
2.7V to 3.6V	2.7V	1.5V	1.5V	$V_{OL} + 0.3V$	$V_{OH} - 0.3V$

NOTE:

1. The measurement points should be V_{IH} or V_{IL} when the input rising or falling time exceeds 2.5ns.

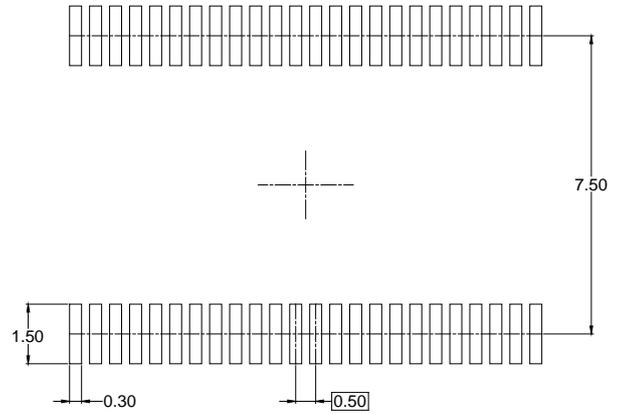
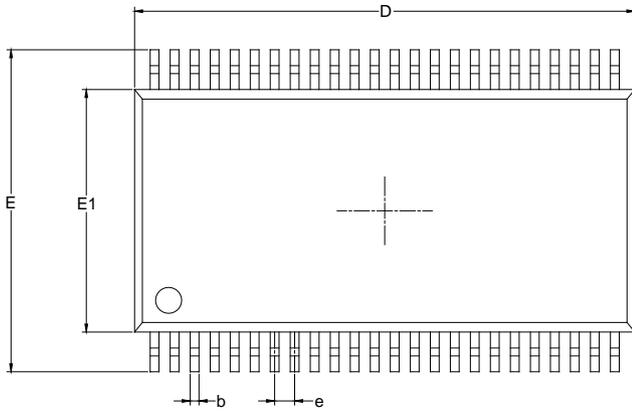
REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

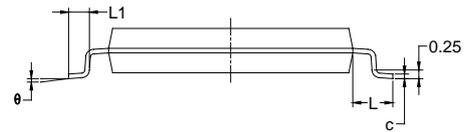
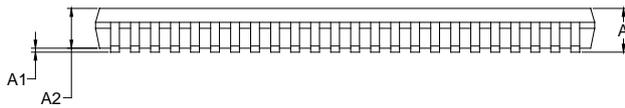
JANUARY 2024 – REV.A.1 to REV.A.2	Page
Updated Dynamic Characteristics section.....	5
JANUARY 2022 – REV.A to REV.A.1	Page
Updated I _I and I _{CC} values in Electrical Characteristics section	4
Changes from Original (MARCH 2021) to REV.A	Page
Changed from product preview to production data.....	All

PACKAGE OUTLINE DIMENSIONS

TSSOP-48



RECOMMENDED LAND PATTERN (Unit: mm)



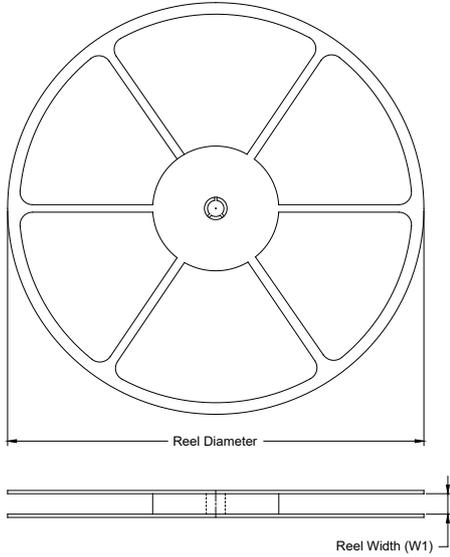
Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A			1.20
A1	0.05	0.10	0.15
A2	0.85	0.95	1.05
b	0.18		0.26
c	0.15		0.19
D	12.40	12.50	12.60
E	7.90	8.10	8.30
E1	6.00	6.10	6.20
e	0.50 BSC		
L	1.00 REF		
L1	0.45		0.75
θ	0°		8°

- NOTES:
 1. Body dimensions do not include mode flash or protrusion.
 2. This drawing is subject to change without notice.

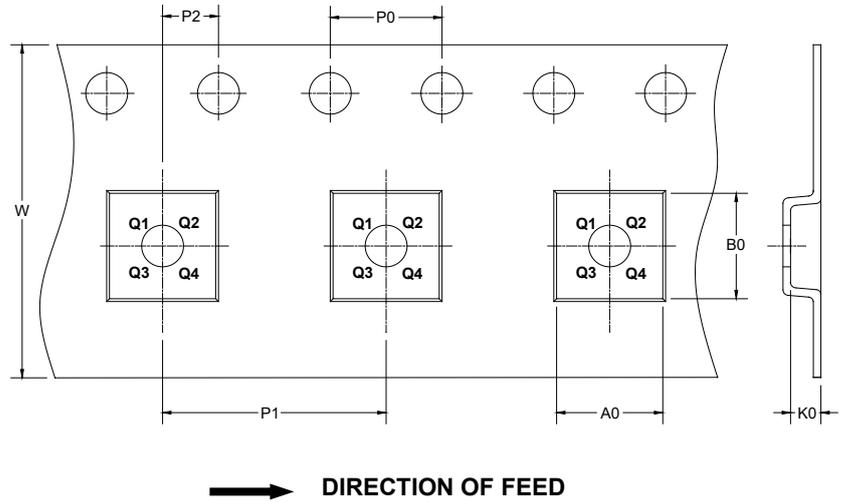
PACKAGE INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

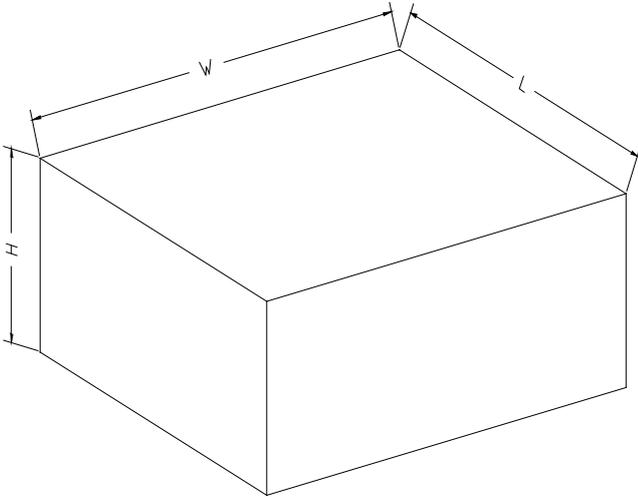
KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TSSOP-48	13"	24.4	8.60	13.00	1.80	4.0	12.0	2.0	24.0	Q1

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PACKAGE INFORMATION

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5

DD0002